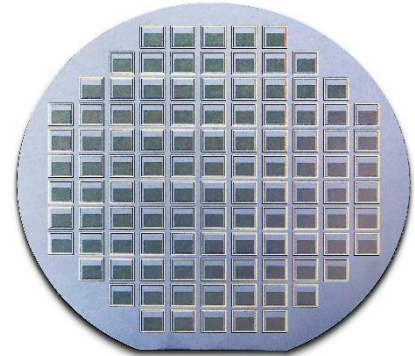


# Wafer level window for IR sensor



Applied to uncooled thermal imaging sensor wafer level package. It can reduce costs effectively and improve efficiency. The following figure shows a typical spectral curve and specific parameters:

Substrate :	Silicon ;
Dimension :	6 or 8inch ;
Cavity depth :	100um or as customer required
Spectrum :	Vertical incidence, $T_{avg} > 80\%$ @8~14 $\mu\text{m}$ ;
Metallization :	Ti/Pt/Au and AuSn alloy film, (Gold tin ratio and film thickness can be customized )
Pattern :	optical and metallized film pattern and the alignment mark can be customized, the line width can reach 10 $\mu\text{m}$ .

